# Cascade

# TESLA300

# 300 mm On-Wafer Power Semiconductor Probing System — Semi-automatic

# Contact Intelligence™

# Up to 10 kV / 200 A with thin-wafer support

Accurate Rds(on) with constant Rc at all temperatures with Contact Intelligence™ Technology

Anti-arcing solutions for wafer, probes and probe cards

#### **Velox**<sup>™</sup> probe station control software

- Innovative operating software for advanced prober operation, temperature control, z-profiling and stepping
- Wafer mapping, automated wafer alignment, and auto XYZ and theta correction for sub-micron stepping
- Workflow Guides: step-by-step guidance through different processes, no matter if these are simple procedures or complex measurements

## Remote operation from home or anywhere in the world

- Safely and easily place probes down in contact with the test pads (full capability with motorized positioners)
- Safely move the wafer to different test sites
- View and manage live microscope viewing of the probes and the wafer
- View Wafer Map test plans
- Initiate remote test programs to gather and analyze test data

#### Connection panels

MicroChamber®

- Coaxial, triaxial, and pin jack feed-troughs available
- · Limit cable strain and motion for measurement stability
- Instrument stays connected to back of panel
- Probe connection made at front of panel

# Simple to re-arrange cabling when needed

- EMI-shielding for low-noise measurements
- Environmentally sealed for moisture-free, low-temperature measurements
- Low volume for the fastest purge
- Light-tight to eliminate the need for a dark box

# AttoGuard®

- Extends instrument guard to completely surround wafer
- Makes the station invisible to the instrument
- Extremely low capacitance and leakage characteristics
- Fast settling times

# PureLine<sup>™</sup> technology

- Enhanced EMI-shielding
- Ideal for low-level IV and CV measurements

#### Compact small footprint

- Integrated vibration isolation for reliable small pad probing
- Integrated system electronics with power loss wafer safety protection

#### TopHat™

- Dark, shielded and frost-free measurement environment
- Allows full access to positioners and microscope at any temperature
- Allows probe adjustments without exposing wafer and chamber to external environment

# **Probes**

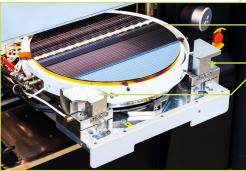
- High voltage (3 kV / 10 kV)
- High current (300 A)
- Low leakage



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#### **TUV-certified probing environment**

- Safety-rated interlock system for high-power testing (meets EN 60947-5-1, EN 60204-1)
- Front, side and rear opening doors for ergonomic test setup and operation
- Side panel with cable pass-through for easy equipment configuration
- Full enclosure design (no light curtain) prevents accidentally tripping the safety interlock and stopping test

#### eVue™ IV Digital Imaging System

- Fast probe set-up with wide field-of-view and single objective in MicroChamber
- Easy navigation with multiple live video views of probes and wafer
- New high-speed focus system for faster and accurate die stepping
- New safety features for probes and usability

## **3D Manual Controls**

- Virtual Platen Lift and XY knobs at front for intuitive, and precise movement of chuck in X, Y, and Z-direction
- Platen Lift enables extremely rapid and intuitive way in performing many alignment tasks, like setting up the contact height

#### Contact Intelligence<sup>™</sup> Technology

- Integrated HTS (High Thermal Stability) reduces probe drift and thermal soak time
- Optional VueTrack  $^{\!\scriptscriptstyle{\text{TM}}}$  reduces thermal soak time (faster time to data)
- Enables unattended test over multiple temperatures

#### Scalable system

- $\bullet$  In-field upgradable wafer loading and automation
- Add test accuracy improvements for increased test performance

# Rollout stage with quick access to auxiliary sites

- Full wafer access via locking roll-out stage
- Two patented auxiliary chucks

#### Patented TESLA chuck technologies

- HV FemtoGuard® 3kV (triax) / 10kV (coax), and low leakage
- Gold-plated MicroVac™ surface for minimal chuck-to-wafer contact resistance
- Prevents thin wafers from curling and breaking
- Wide range of temperature options from -60°C to 300°C

#### Auxiliary chucks

- High voltage 10 kV compatible multi-purpose mounts for substrates (cleaning, contact)
- Automated probe cleaning capabilities



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